# MSKSEMI 美森科













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## BAT08-XXXB(MS)

Product specification





#### **DESCRIPTION**

The BAT08-XXXB(MS) SCR series with the parallel resis tor between Gate and Cathode are especially recommended for use on straight hair, igniter, anion generator, etc.

#### **MAIN FEATURES**

Symbol	Value	Unit
I <sub>T(RMS)</sub>	8	А
VDRM /VRRM	600/800	V

#### **Reference News**

PACKAGE OUTLINE	Pin Configuration	Marking		
No. of the last of	T2(2) T1(1)	MSKSEMI BAT08-600B MS XXX	MSKSEMI BAT08-800B MS XXX	
2 3		BTA08-600B(MS)	BTA08-800B(MS)	

**Notes:XXX** represents the order code.

#### **ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Value	Unit
Storage junction temperature range	Tstg	-40 - 150	$^{\circ}$ C
Operating junction temperature range	Tj	-40 - 125	$^{\circ}$ C
Repetitive peak off-state voltage (Tj=25℃)	VDRM	600/800	V
Repetitive peak reverse voltage (T <sub>j</sub> =25℃)	VRRM	600/800	V
Non repetitive surge peak Off-state voltage	VDSM	V <sub>DRM</sub> +100	V
Non repetitive peak reverse voltage	Vrsm	V <sub>RRM</sub> +100	V
RMS on-state Current (TC=95°C)	I <sub>T(RMS)</sub>	8	Α
Non repetitive surge peak on-state current (full cycle, F=50Hz)	Ітѕм	80	А
Pt value for fusing (tp=10ms)	Pt	32	A <sup>2</sup> s
Critical rate of rise of on-state current (I <sub>G</sub> =2×I <sub>GT</sub> )	dl/dt	50	A/µs
Peak gate current	lgм	4	Α
Average gate power dissipation	P <sub>G(AV)</sub>	1	W
Peak gate power	Рдм	5	W



## **ELECTRICAL CHARACTERISTICS** ( $T_j$ =25 $^{\circ}$ C unless otherwise specified)

#### 3 Quadrants

Symbol	Test Condition	Quadrant		Value	Unit
lgт	V <sub>D</sub> =12V R <sub>L</sub> =33Ω	I - II-III	MAX	50	mA
V <sub>GT</sub>	VD=12V RL=3312	I - II-III	MAX	1.5	V
V <sub>GD</sub>	$V_D=V_{DRM} T_j=125 ^{\circ}\mathbb{C}$ RL=3.3K $\Omega$	I - II-III	MIN	0.2	V
	1 4 01	I -III	MAY	70	т Л
l.	L   lg=1.2lgт		MAX	90	mA
lн	Iтм=100mA		MAX	60	mA
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125°C		MIN	1000	V/µs

#### 4 Quadrants

Symbol	Test Condition	Quadrant		Value	Unit
lor		I - II-III	MAX	50	mΛ
Ідт	VD=12V RL=33Ω	IV	IVIAX	70	mA
V <sub>GT</sub>		ALL	MAX	1.5	V
V <sub>GD</sub>	$V_D = V_{DRM} T_j = 125 ^{\circ}C$ ALL $R = 3.3 K\Omega$		MIN	0.2	V
L	1 4 01	I -III-IV	MAX	70	mA
L Ig=1.2Igт	IG=1.2IGT	IVIAX	90	IIIA	
Ін	I <sub>тм</sub> =200mА		MAX	60	mA
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125℃		MIN	500	V/µs

#### STATIC CHARACTERISTICS

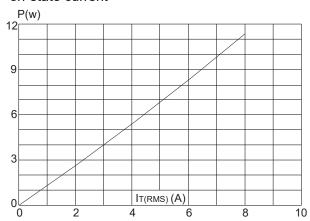
Symbol	Parameter		Value(MAX)	Unit
V <sub>TM</sub>	Iтм =11Atp=380μs Т <sub>j</sub> =25℃		1.5	V
IDRM		T <sub>j</sub> =25℃	5	μA
IRRM	$V_D = V_{DRM} V_R = V_{RRM}$	T <sub>j</sub> =125℃	1	mA

#### THERMAL RESISTANCES

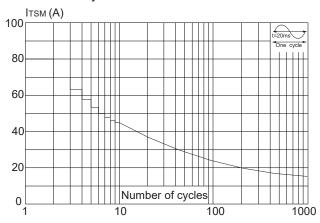
Symbol	Parameter	Value	Unit
Rth(j-c)	junction to case(AC)	2.7	°C/W



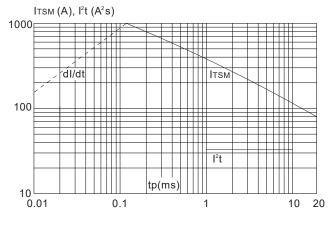
**FIG.1:** Maximum power dissipation versus RMS on-state current



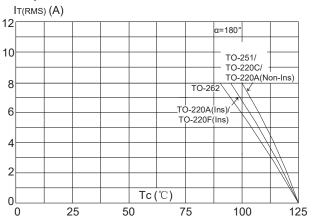
**FIG.3:** Surge peak on-state current versus number of cycles



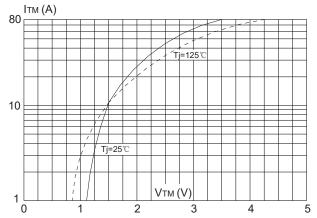
**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<20ms, and corresponging value of I<sup>2</sup>t (dI/dt < 50A/µs)



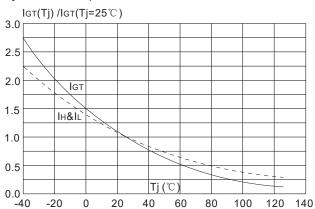
**FIG.2:** RMS on-state current versus case temperature



**FIG.4:** On-state characteristics (maximum values)

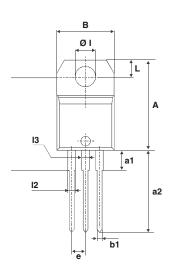


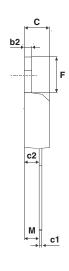
**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature





## PACKAGE MECHANICAL DATA





	DIMENSIONS					
REF.	Millimeters		rs	Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	15.20		15.90	0.598		0.625
a1		3.75			0.147	
a2	13.00		14.00	0.511		0.551
В	10.00		10.40	0.393		0.409
b1	0.61		0.88	0.024		0.034
b2	1.23		1.32	0.048		0.051
С	4.40		4.60	0.173		0.181
с1	0.49		0.70	0.019		0.027
c2	2.40		2.72	0.094		0.107
е	2.40		2.70	0.094		0.106
F	6.20		6.60	0.244		0.259
ØI	3.75		3.85	0.147		0.151
14	15.80	16.40	16.80	0.622	0.646	0.661
L	2.65		2.95	0.104		0.116
12	1.14		1.70	0.044		0.066
13	1.14		1.70	0.044		0.066
М		2.60			0.102	

#### **REEL SPECIFICATION**

P/N	PKG	QTY
BAT08-XXXB(MS)	TO-220	50/One tube 1000/a box of



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